



SG7350D

Thermal Conductive RF PCB Used Laminate Material

FEATURES

- Glass-reinforced PTFE and ceramic dielectric.
- Excellent high frequency performance.
- Enhanced thermal conductivity.
- Stable electrical properties versus frequency.
- Low Z-axis expansion and excellent dimensional stability.
- Compatible with lead-free process

APPLICATIONS

Passive Components
Power Amplifiers.
Microwave Combiner and Power Dividers
LNA/LNB

GENERAL PROPERTIES

Property	Test Method	Condition	Units	Direction	Typical Value
Dk(Process)	IPC-TM-650 2.5.5.5	10 GHz/23°C	—	Z	3.55
Df(Process)	Clamped Stripline	10 GHz/23°C	—	Z	0.0022
TCDk	IPC-TM-650 2.5.5.5	-25°C to 125°C	ppm/°C	Z	-14
Volume Resistivity	IPC-TM-650 2.5.17.1	COND A	MΩ·cm		5.8×10^6
Surface Resistivity	IPC-TM-650 2.5.17.1	COND A	MΩ		2.9×10^7
Electrical Strength	IPC-TM-650 2.5.6.2	COND A	KV/mm	Z	30
Dielectric Breakdown	IPC TM-650 2.5.6	COND A	kV	Z	40
Flexural Strength	IPC-TM-650 2.4.4	COND A	MPa	X Y	100 80
Coefficient of Thermal Expansion	IPC-TM-650 2.4.41	25 to 150°C	ppm/°C	X Y	9 8
	IPC-TM-650 2.4.24	25 to 150°C	ppm/°C	Z	25
Td	IPC-TM-650 2.4.24.6	5% loss	°C		565
Thermal Conductivity	ASTM D5470	0.508mm	W/(m·K)		0.80
Moisture Absorption	IPC-TM-650 2.6.2.1	D-24/23°C	%		0.05
Copper Peel Strength	IPC-TM-650 2.4.8	after solder float 1 oz. ED Foil	N/mm		0.90
Flammability	UL 94				V-0

(1) All the typical value is based on the 0.508mm(0.020") specimen, and the specification sheet is based on IPC4103.

(2) Typical values are a representation of an average value for the population of the property.

PRODUCT SPECIFICATION

Standard Thickness	Standard Panel Size	Standard Copper Cladding
0.010" (0.254mm) 0.020" (0.508mm) 0.030" (0.762mm) 0.040" (1.016mm) 0.060" (1.524mm) Additional thickness may be available upon request.	18"×24",36"×48", 40"×48", Additional panel sizes may be available upon request.	½ oz. (17µm) ,1 oz. (35µm) Low profile, ED copper foil.